

6249052

Fig. 1A

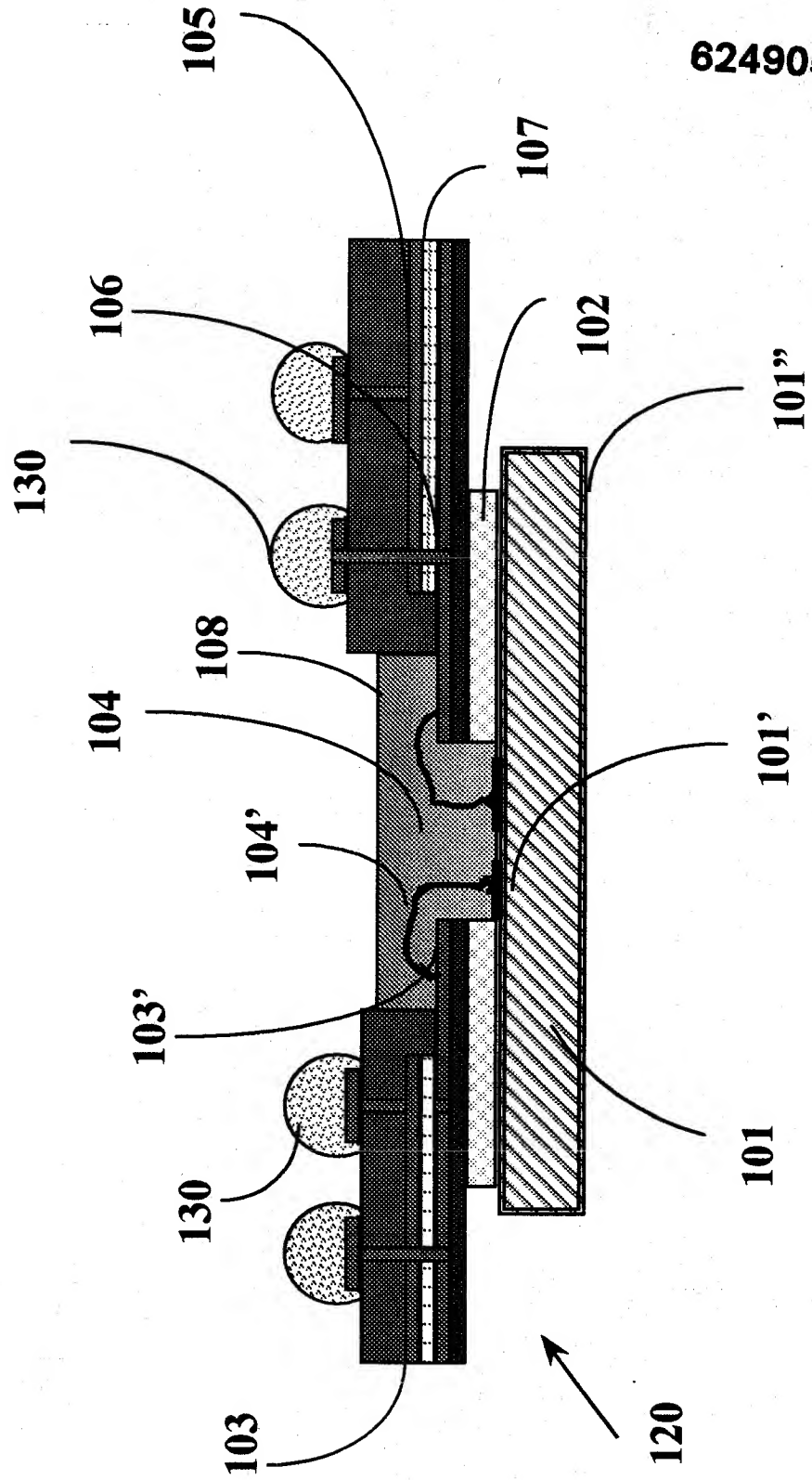
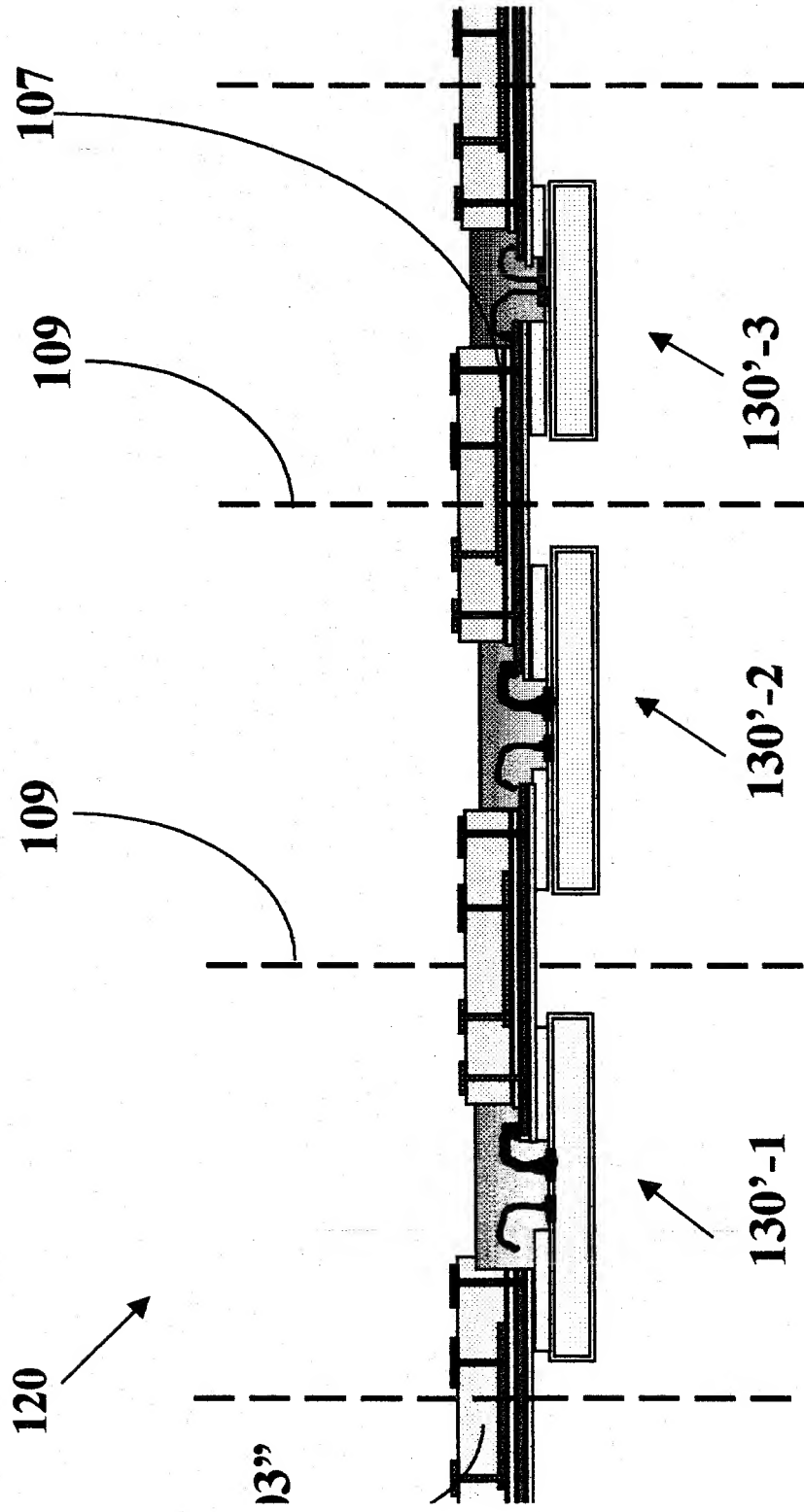


Fig.1B



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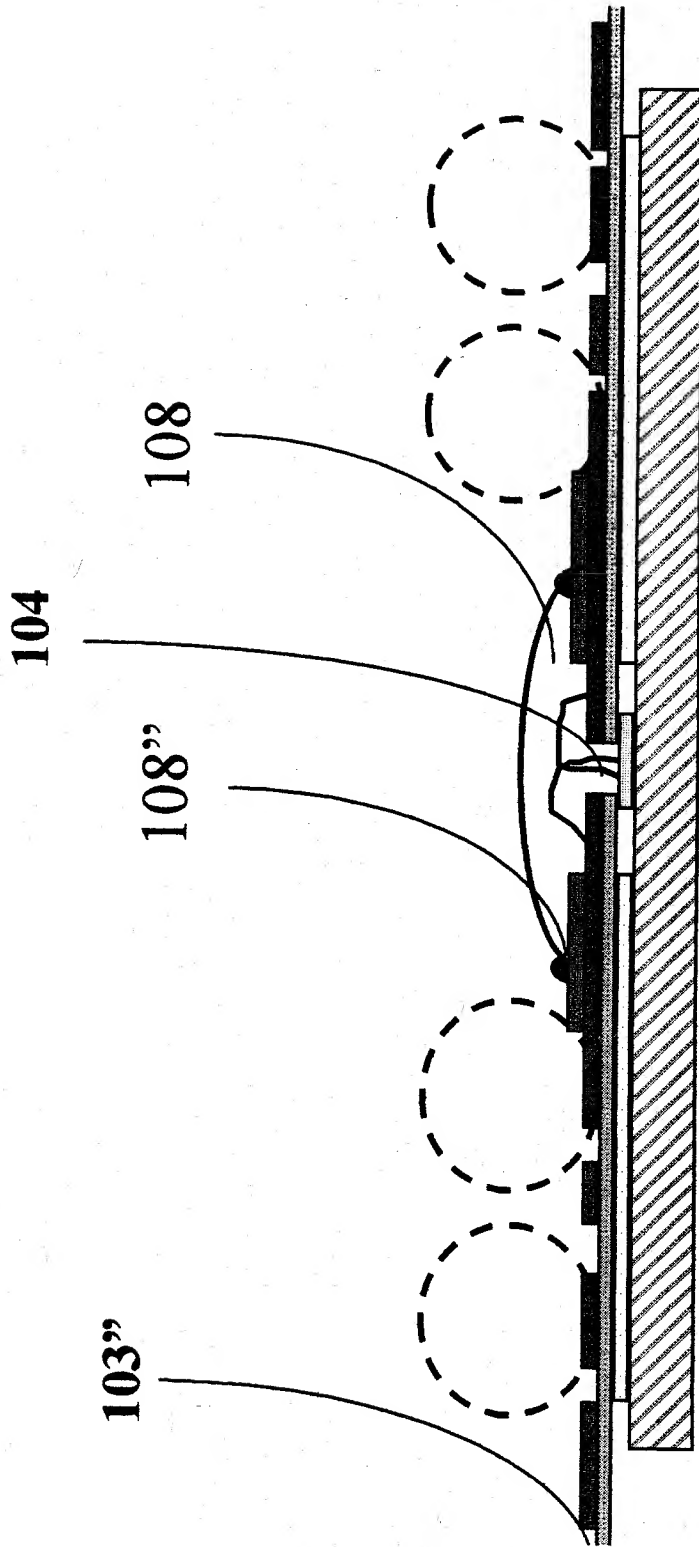


Fig. 1C

Fig. 1D

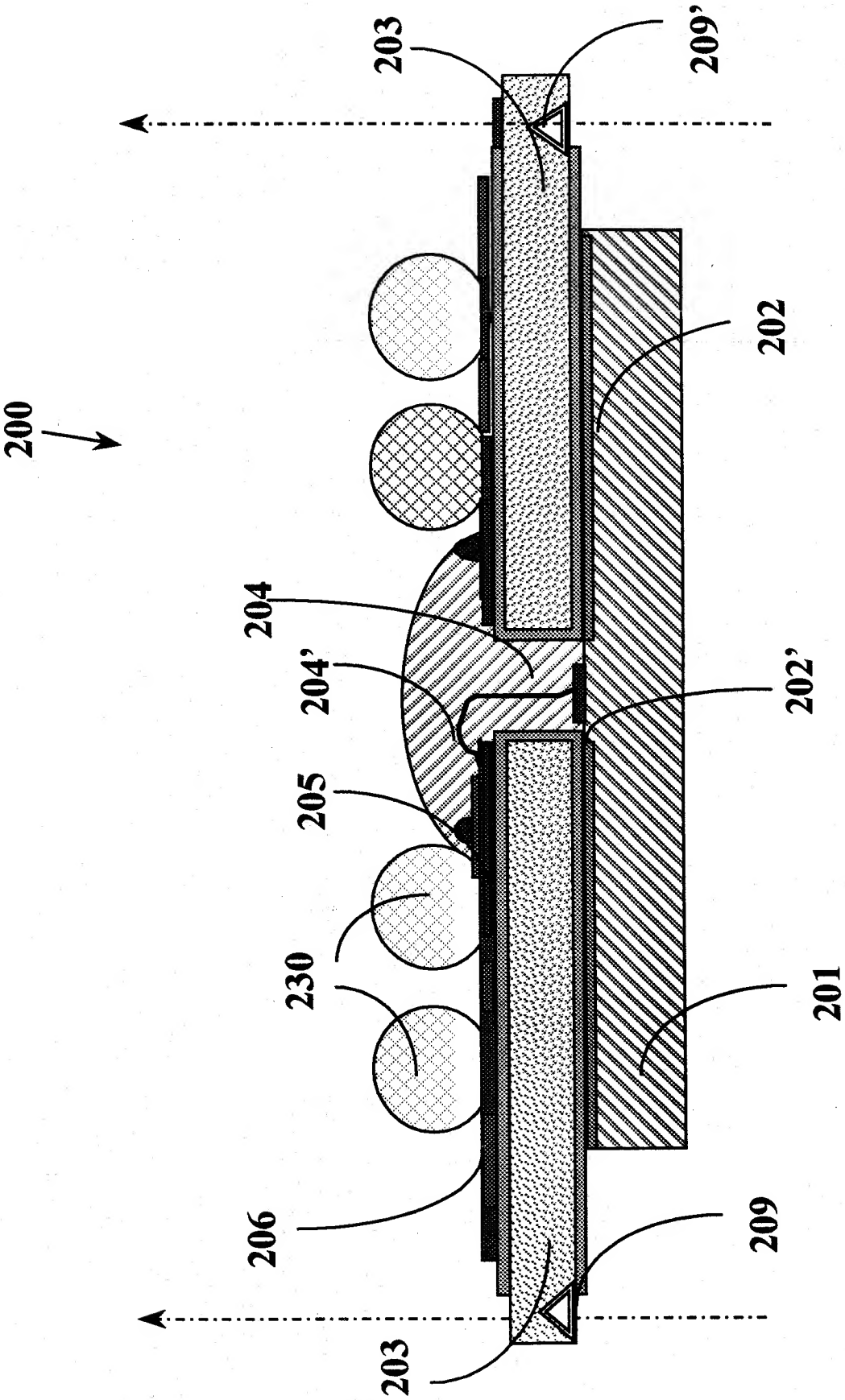


Fig. 2A

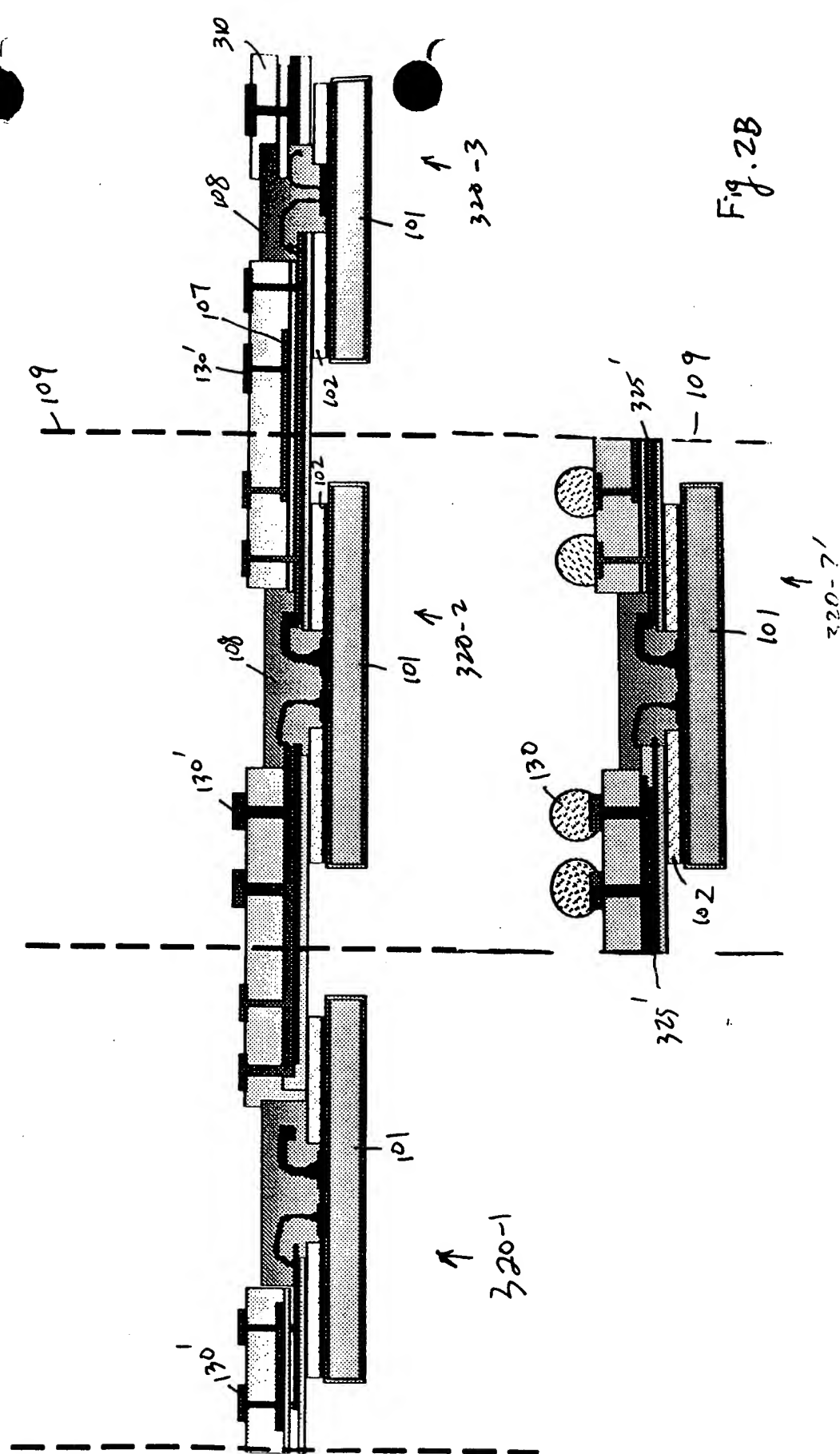


Fig. 2C

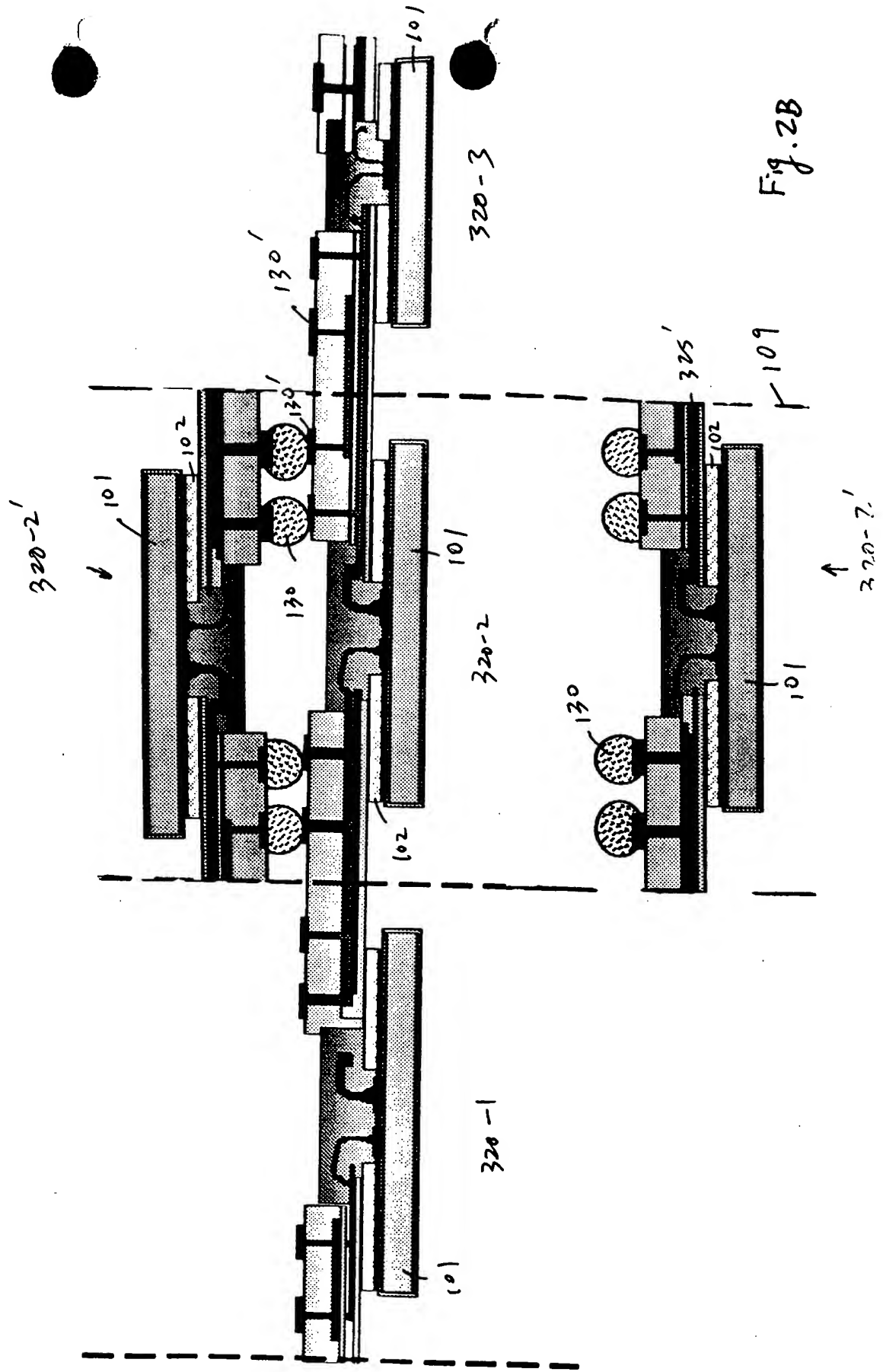


Fig. 2B

300

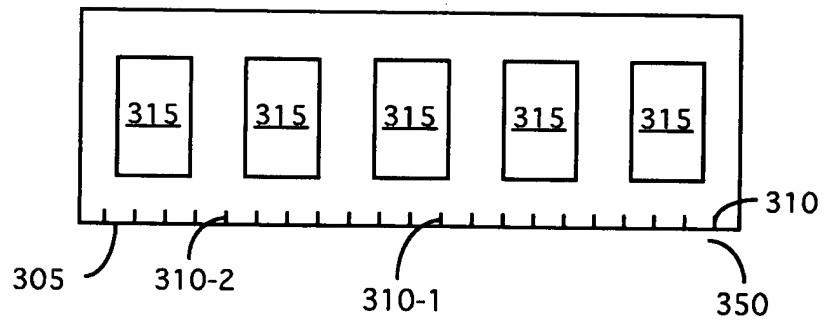


FIG. 3A

300

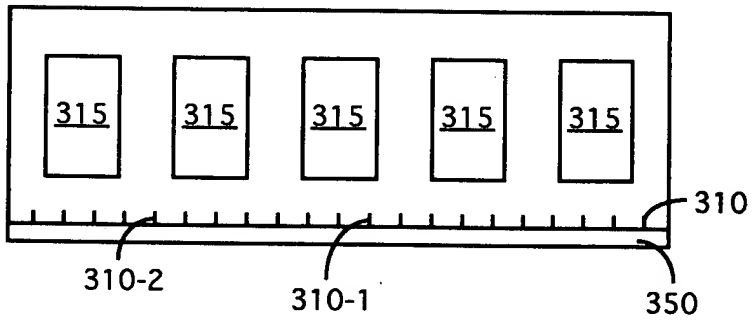


FIG. 3B

CONVENTIONAL MCM FLOW

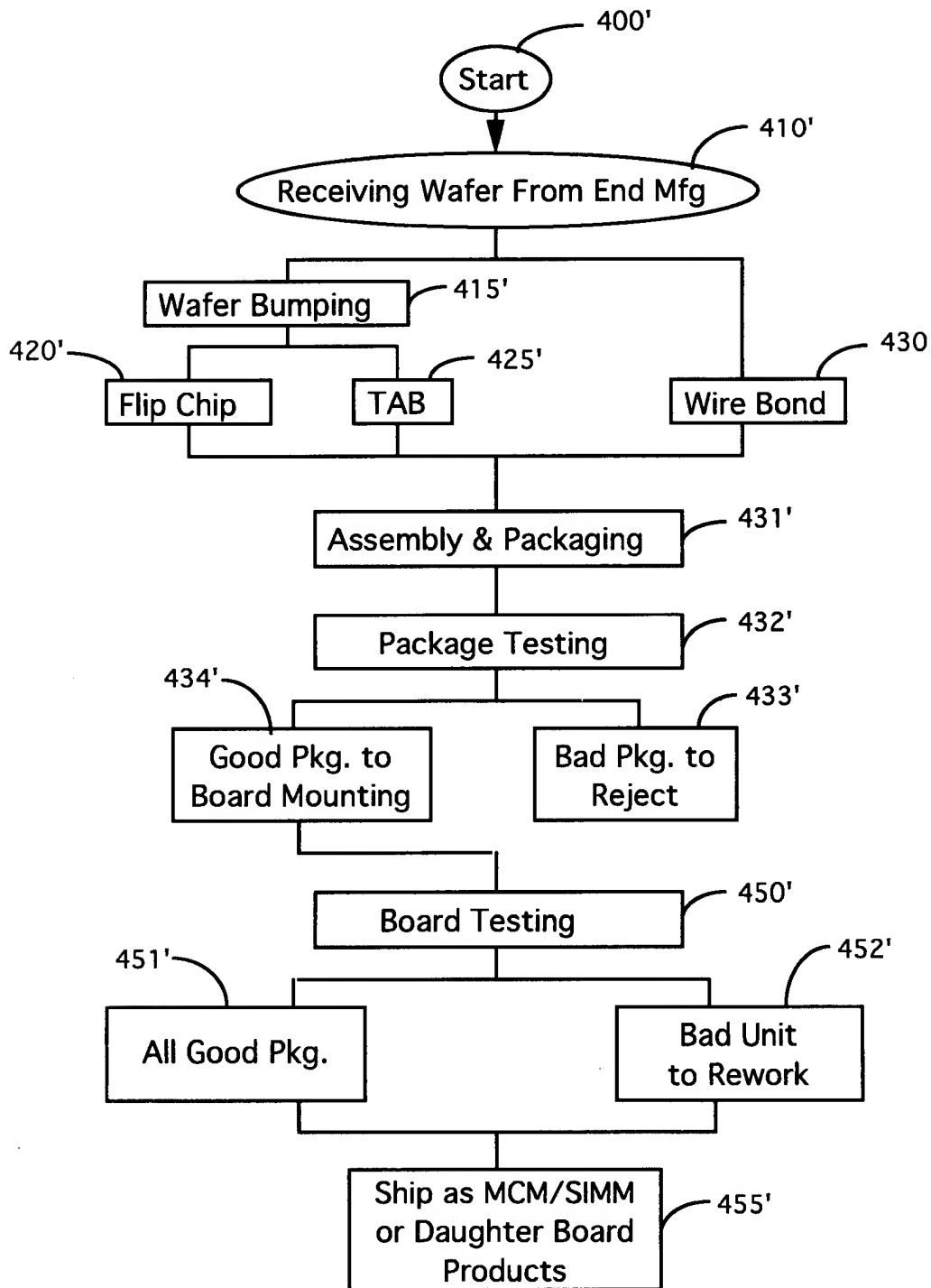


FIG. 4A

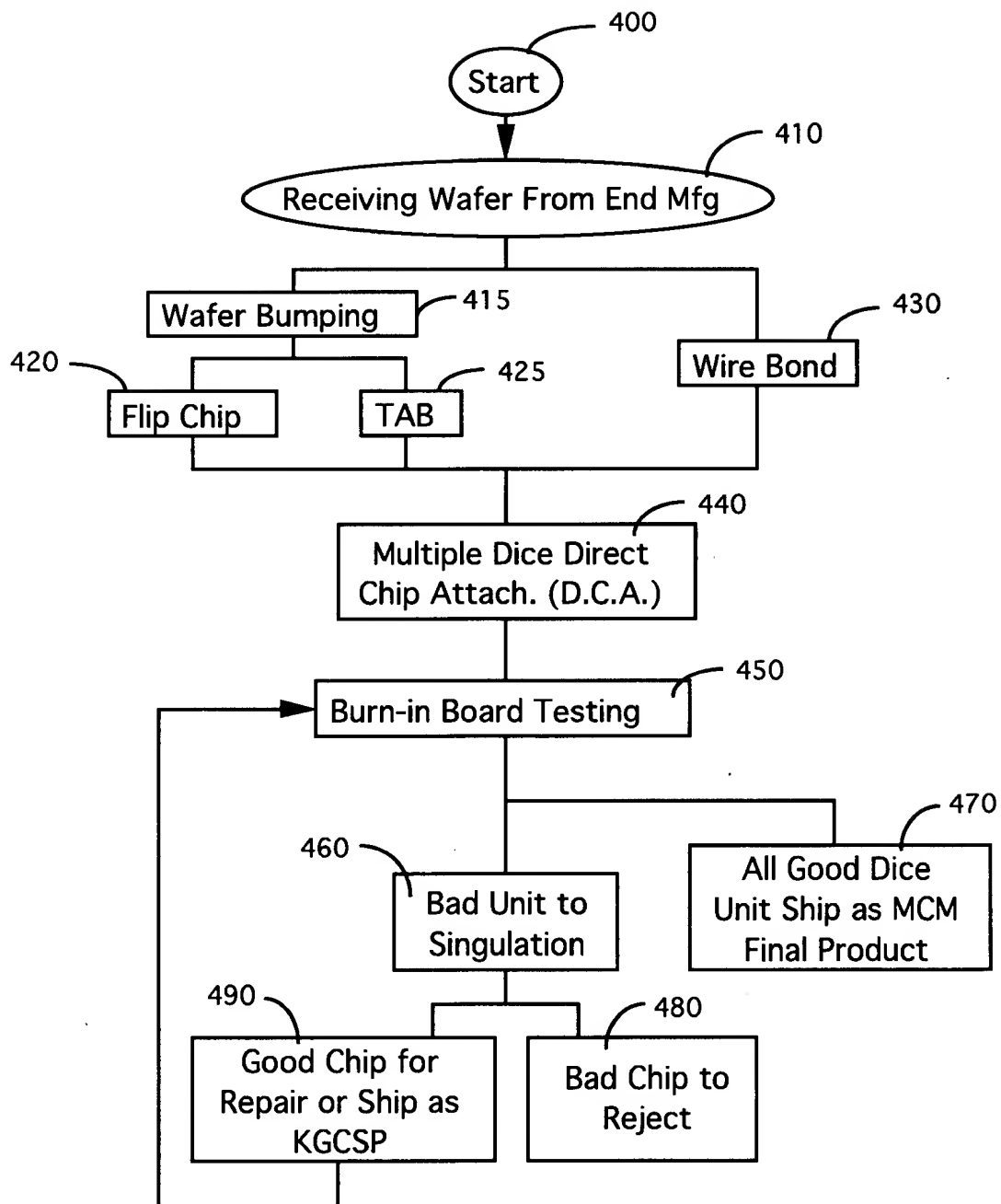


FIG. 4B

Fig. 5

Very Stringent Requirements for SMT Packages

Package Qualification Tests with Level 3 Preconditioning

↓
10 X Temperature Cycle (-65 to +150 deg.C)

↓
Bake of 125 deg.C for 24 Hrs

↓
Temperature Humidity Soak (30 deg.C, 60% RH, 192Hrs)

↓
Vapor Phase (215 deg. C, 60 Sec., 3 Passes)

Thermal Shock Test

Liq. to Liq. -65 to +150 deg.C

1000 Cycles

Temperature Cycle Test

Air to Air, -65 to + 150 deg.C

1,000 Cycles

Autoclave Test

121 deg C,

100% RH

15 PSIG

96 Hrs

Temp.Humidity Bias

85 deg C/85% RH

3.3 Volts

1008 Hrs.

These requirements will not applied on edge connected sub-system such as SIMM/DIMM, PCMCIA or Slot 2 formats.